


Full Material Declaration for attached parts list

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	<p>Diotec Semiconductor AG DUNS number: 330866844 -, Kreuzmattenstr. 4, Heitersheim, B.-W., 79423, Germany Declarations authorised by Udo Steinebrunner, Product Manager, -</p>
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Declaration effective from: 06 December 2016 [Approved: 23 May 2025 14:21 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.32%	TITANIUM	7440-32-6	0.1%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	0.6%
			SILVER, ELEMENTAL	7440-22-4	2.4%
			Silicon	7440-21-3	96.9%
			Silver	7440-22-4	2.5%
Die attach	Lead and Lead alloys	0.641%	Tin	7440-31-5	5%
			Lead Exempt from other regulatory requirements EU RoHS Exemption 27 Exempt from other regulatory requirements	7439-92-1	92.5%
			Carbon black	1333-86-4	0.4%
			ANTIMONY TRIOXIDE Exempt from other regulatory requirements	1309-64-4	1%
			Phenol, 4,4'-(1-methylethylidene)bis[2,6-dibromo-, polymer with (chloromethyl)oxirane Exempt from other regulatory requirements	40039-93-8	1%
Encapsulation	EP (Epoxy resin)	19.811%	Phenol, polymer with formaldehyde	9003-35-4	6.5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	13%
			Quartz sand	60676-86-0	15%

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Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Leadfinish	Tin plating	2.117%	Quartz (SiO ₂)	14808-60-7	63.1%
			Tin	7440-31-5	100%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	77.111%	Copper	7440-50-8	100%

Attached parts list

Part number	Part name
DO-15 (ZM)	Diode axial